

IN THE CLAIMS:

Cancel claim 13.

Amend claim 11 as follows:

11. (Amended) A semiconductor device, comprising:

 a semiconductor chip having a top surface, said semiconductor chip carrying a first electrode;

 a circuit substrate attached to a top surface of said semiconductor chip, said circuit substrate carrying thereon a predetermined conductor pattern including a second electrode and a third electrode;

 a solder resist layer provided on said circuit substrate;

 a resin layer intervening between said top surface of said semiconductor chip and said circuit substrate;

 a spherical electrode formed in an opening in said solder resist layer on said circuit substrate in correspondence to said third electrode;

 a bonding wire electrically interconnecting said second electrode of said predetermined conductor pattern on said circuit substrate and said first electrode on said semiconductor chip;

 and

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a resin potting encapsulating said bonding wire including said first and second electrodes, said chip and said resin potting being defined by a common edge surface when viewed in a direction substantially perpendicular to a principal surface of said substrate, wherein said resin layer has a composition substantially identical with a composition of said resin potting.